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0 PN=JP 8968984  
S5 3 AN, PN=JP 8968984  
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**5/5/1 (Item 1 from file: 351)**  
DIALOG(R) File 351:Derwent WPI  
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008457343 \*\*Image available\*\*  
WPI Acc No: 1990-344343/199046  
XRAM Acc No: C90-149307  
XRPX Acc No: N90-263195

**Transfer and holding device for semiconductor wafer - comprises heat-resistant concave body and heat-insulating means**  
Patent Assignee: FUJITSU LTD (FUIT )  
Number of Countries: 001 Number of Patents: 001  
Patent Family:  
Patent No Kind Date Applicat No Kind Date Week  
JP 2248039 A 19901003 JP 8968984 A 19890320 199046 B

Priority Applications (No Type Date): JP 8968984 A 19890320

Abstract (Basic): JP 2248039 A

The device comprises a heat-resistant concave main body including supporting parts for supporting a semiconductor wafer, and a heat insulating means covering an upper zone of the main body.

USE - Productivity and yield of wafers are improved. (8pp  
Dwg.No.1/6)

Title Terms: TRANSFER; HOLD; DEVICE; SEMICONDUCTOR; WAFER; COMPRISE; HEAT; RESISTANCE; CONCAVE; BODY; HEAT; INSULATE

Derwent Class: L03; Q77; U11

International Patent Class (Additional): C21D-001/00; F27D-003/00;  
H01L-021/22

File Segment: CPI; EPI; EngPI

**5/5/2 (Item 1 from file: 345)**  
DIALOG(R) File 345:Inpadoc/Fam.& Legal Stat  
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9517909  
Basic Patent (No,Kind,Date): JP 2248039 A2 901003 <No. of Patents: 002>

PATENT FAMILY:

JAPAN (JP)

Patent (No,Kind,Date): JP 2248039 A2 901003  
TRANSFER HOLDING TOOL FOR SEMICONDUCTOR WAFER (English)  
Patent Assignee: FUJITSU LTD  
Author (Inventor): HARA AKITO  
Priority (No,Kind,Date): JP 8968984 A 890320  
Applic (No,Kind,Date): JP 8968984 A 890320  
IPC: \* H01L-021/22; C21D-001/00; F27D-003/00  
Derwent WPI Acc No: ; C 90-344343  
JAPIO Reference No: ; 140573E000056  
Language of Document: Japanese  
Patent (No,Kind,Date): JP 2748325 B2 980506  
Patent Assignee: FUJITSU LTD  
Author (Inventor): HARA AKITO  
Priority (No,Kind,Date): JP 8968984 A 890320  
Applic (No,Kind,Date): JP 8968984 A 890320  
IPC: \* H01L-021/22; H01L-021/322  
Language of Document: Japanese

**5/5/3 (Item 1 from file: 347)**  
DIALOG(R) File 347:JAPIO

03272539 \*\*Image available\*\*  
TRANSFER HOLDING TOOL FOR SEMICONDUCTOR WAFER

PUB. NO.: 02-248039 [JP 2248039 A]  
PUBLISHED: October 03, 1990 (19901003)  
INVENTOR(s): HARA AKITO  
APPLICANT(s): FUJITSU LTD [000522] (A Japanese Company or Corporation), JP  
(Japan)  
APPL. NO.: 01-068984 [\*JP 8968984\*]  
FILED: March 20, 1989 (19890320)  
INTL CLASS: [5] H01L-021/22; C21D-001/00; F27D-003/00  
JAPIO CLASS: 42.2 (ELECTRONICS -- Solid State Components); 12.2 (METALS --  
Metallurgy & Heat Treating); 24.2 (CHEMICAL ENGINEERING --  
Heating & Cooling)  
JOURNAL: Section: E, Section No. 1015, Vol. 14, No. 573, Pg. 56,  
December 19, 1990 (19901219)

ABSTRACT

PURPOSE: To reduce the generation of a dislocation crystal defect part, which is propagated to the central part of a semiconductor wafer, as low as possible by a method wherein supporting parts for the wafer and an axis to show the crystalline orientation of the wafer are made to have no relation with each other.

CONSTITUTION: A covering heat insulating means 13 to cover the upper region of a placement main body part 11 is provided and each semiconductor wafer 14 is placed between dummy wafers 25. Moreover, the wafer 14 is placed on the main body part 11 in such a way that extension lines 11 to 15 that link the vicinity of the center of the wafer 14 with each supporting part 12a to 12e and an axis C to show the crystalline orientation of the wafer 14 do not intersect orthogonally to each other within a plane including the axial direction of the parts 12a to 12e. Owing to this, in case a transfer holding tool, on which the wafer 14 is placed, is put out from or in a hot furnace in a high-temperature atmosphere, a space, which is formed of the part 11, the means 13, the wafers 25 and the wafer 14, always fulfills an adiabatic effect and the wafer 14 can be protected from a change in a state, such as an abrupt temperature rise, an abrupt temperature drop and the like.